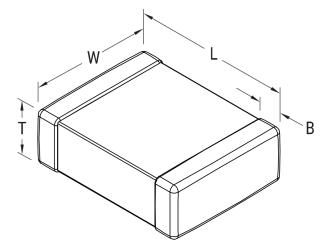


CKC33C822KCGAC7210

KC-LINK Comm COG, Ceramic, 8200 pF, 10%, 500 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640



Click here for the 3D model.

Dimensions		
Chip Size	3640	
L	9.3mm +/-0.6mm	
W	10.2mm +/-0.4mm	
т	2mm +/-0.20mm	
В	1.27mm +/-0.4mm	

Packaging Specifications	
n, Plastic Tape	

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	790 mg
Shelf Life	78 Weeks
MSL	1

Specifications			
Capacitance	8200 pF		
Measurement Condition	1 kHz 1.0Vrms		
Capacitance Tolerance	10%		
Voltage DC	500 VDC		
Dielectric Withstanding Voltage	750 VDC		
Temperature Range	-55/+150°C		
Temperature Coefficient	COG		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms		
Dissipation Factor	0.1% 1 kHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour		
Insulation Resistance	100 GOhms		

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.